

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)**

ATTY. DOCKET NO.
005918 USA/
FPS/MMCS/APC

SERIAL NO.
09/943,955

APPLICANT
SHANMUGASUNDRAM et al.

FILING DATE
August 31, 2001

GROUP
1765



U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
L.J.M-E	4,957,605	09/18/90	Hurwitt et al.			04/17/89
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EXAMINER

Lynette T. Ames-Evneri

DATE CONSIDERED

12/27/2004

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EXAMINER <i>Lynette J. Ung-Evanni</i>			DATE CONSIDERED 12/27/2004			

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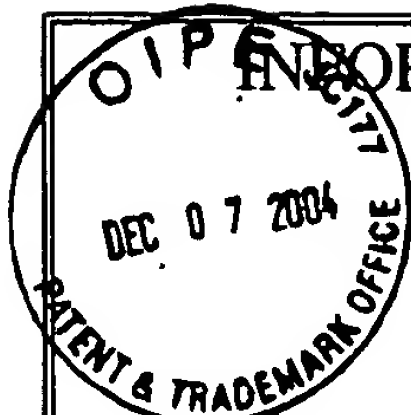
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EXAMINER <i>Lynette J. Nguyen-Sumner</i>				DATE CONSIDERED <i>12/27/2004</i>			

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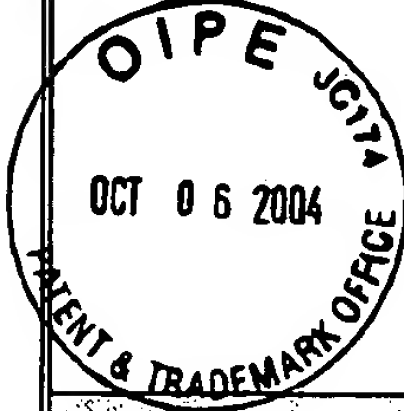
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